ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INFORMATION ADDRESS	annockburn, Illinois.	All rights reserved u entions.	nder both	This docume level parts, t	ent is a declaration	ion of the su	ibstances v s all lower	within the manufactur level materials for wi	rer listed it hich the m	tem. Note: it nanufacturer	f the item is an as has engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information				
Supplier Information												
Company name* Company unique ID			D Uniq		Unique ID Authority				Response Date*			
onsemi									2023-06-08			
Contact Name	tet Name Title - Contact			]	Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Enviro Comp			Compliance J		NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			Phor		Phone - Repre	ne - Representative*			Email - Representative*			
Product-Env-Stewards	viro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	mber Mfr Item Number		r Mfr Item Name		Effective Date	Version	M	Manufacturing Site		Weight*	UOM	Unit Type
]	FS7140-02G-XTP	7140-02G-XTP FS7140-02G CLO			2023-06-08 PHG		HG	:	149.22	mg	Each	
Manufacturing Proccess Information									·			
Terminal Plating / Grid Array Material	Array Material Terminal Base Alloy		J-STD-020 MSL	Rating	Peak Proc	ocess Body Temperature Max Time at Peak		Temperature Number of Reflow Cycles		cles		
Matte Tin (Sn) - annealed CU Alloy		2		260		С	30	secon	ds 3			
Comments												
ATTENTION: MSL 2 Rated item requires Dry	v Pack (after electrica	l test)										
For more information regarding material com	position please refer t	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Interial Weight Unit of Measure Level Substance		Substance	CAS	Exempt	Weight	Unit of Measure		
Die	7.55	mg	Supplier	Silicon (Si)	7440-21-3		7.55	mg	
Die Attach	2.59	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.5957	mg	
			Supplier	Silver (Ag)	7440-22-4		1.9943	mg	
Lead Frame	42.6	mg	Supplier	Zinc (Zn)	7440-66-6		0.0426	mg	
			Supplier	Iron (Fe)	7439-89-6		0.9798	mg	
			Supplier	Copper (Cu)	7440-50-8		41.535	mg	
			Supplier	Phosphorus (P)	7723-14-0		0.0426	mg	
Mold Compound-Black	94.53	mg		Epoxy Phenol Resin	proprietary data		9.9256	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		84.6043	mg	
Plating	1.65	mg	Supplier	Tin (Sn)	7440-31-5		1.65	mg	
Wire Bond - Au	0.3	mg	Supplier	Gold (Au)	7440-57-5		0.3	mg	